



Click [here](#) for the 3D model.

### Dimensions

Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
T	0.78mm +/-0.10mm
S	0.75mm MIN
B	0.5mm +/-0.25mm

### Packaging Specifications

Packaging	T&R, 330mm, Paper Tape
Packaging Quantity	15000

### General Information

Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	11 mg
Shelf Life	78 Weeks
MSL	1

### Specifications

Capacitance	3300 pF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	50 VDC
ESD Level per AEC-Q200	16,000 V ESD Level
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms